

FIG. 1A

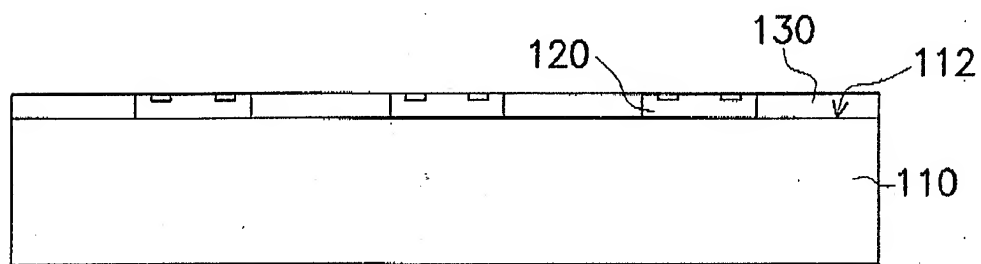


FIG. 1B

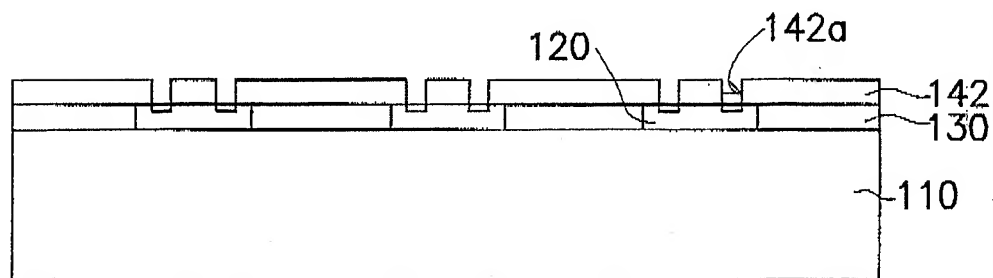


FIG. 1C

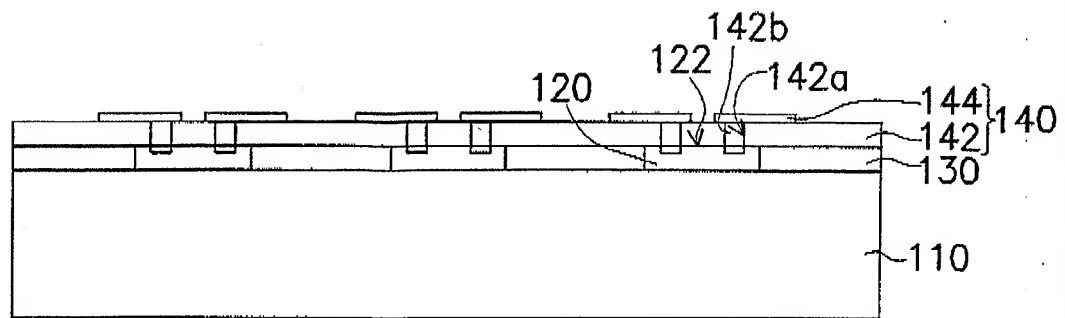


FIG. 1D

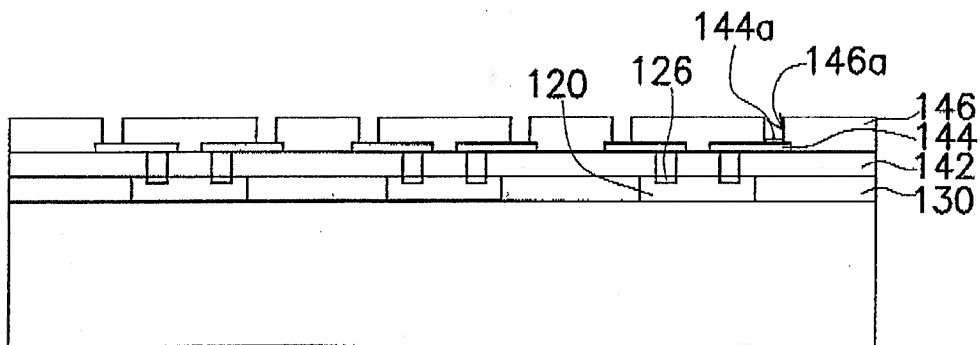


FIG. 1E

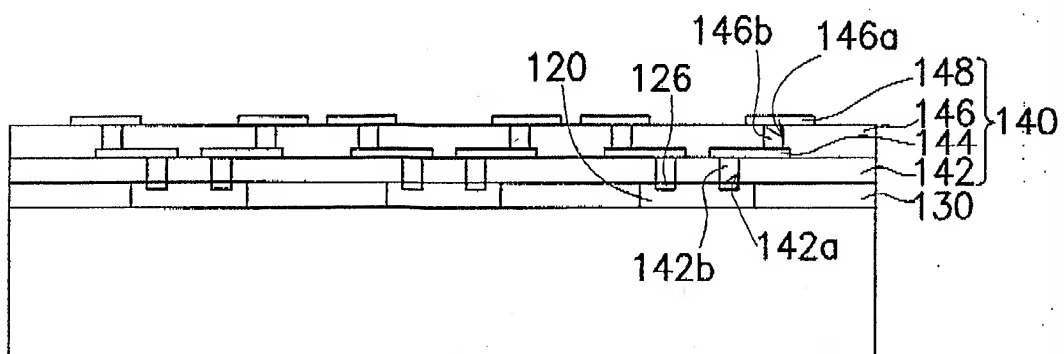


FIG. 1F

A cross-sectional view of a semiconductor device. The device consists of a substrate 120, which is a thick rectangular block at the bottom. On top of the substrate, there is a series of rectangular blocks (spacers) arranged in a row. Each rectangular block has a circular component (possibly a contact or a pad) on top of it. The circular components are connected to a common line or bus that runs along the top of the device. The substrate 120 is labeled with a reference numeral 120.

FIG. 11

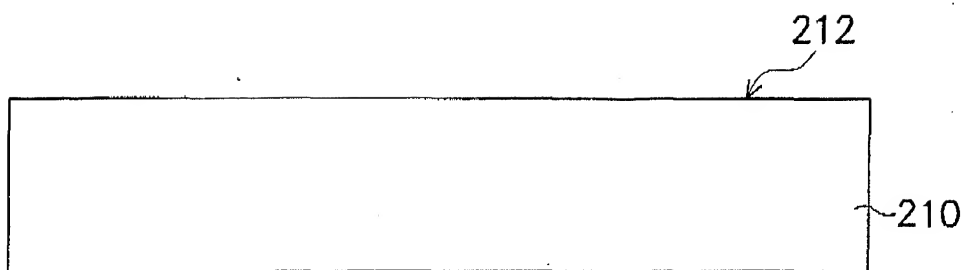


FIG. 2A

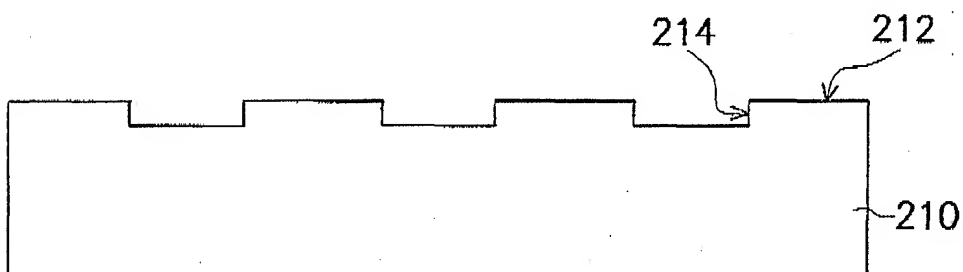


FIG. 2B

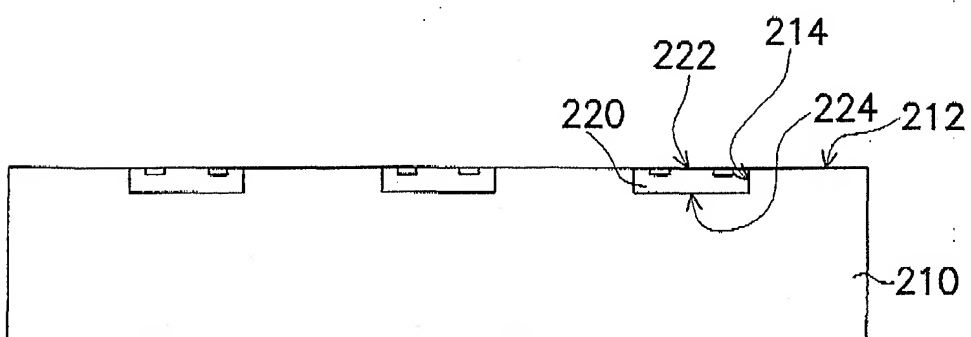


FIG. 2C

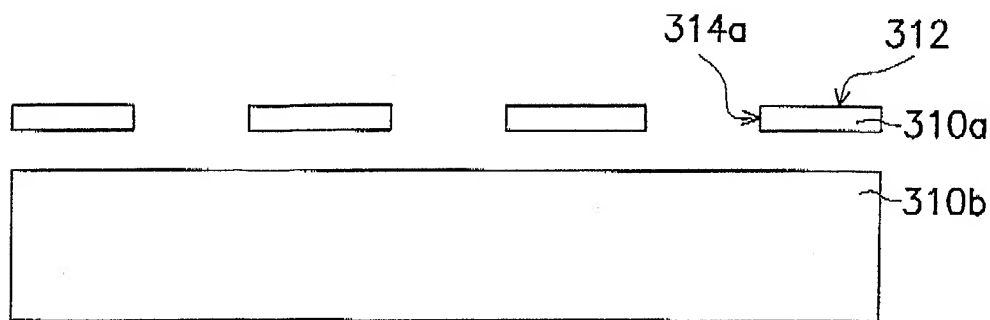


FIG. 3A

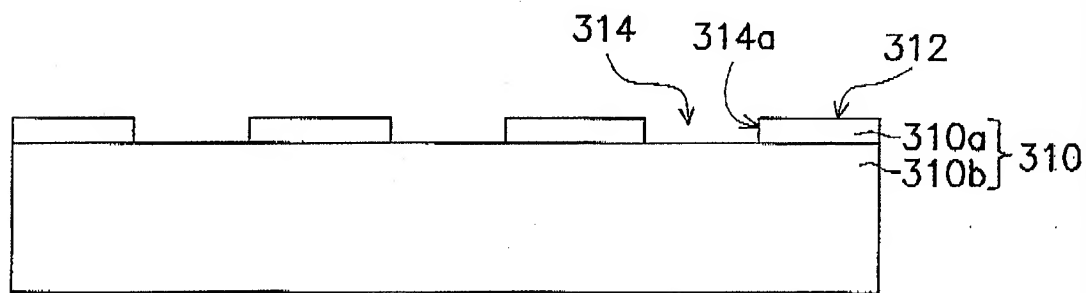


FIG. 3B

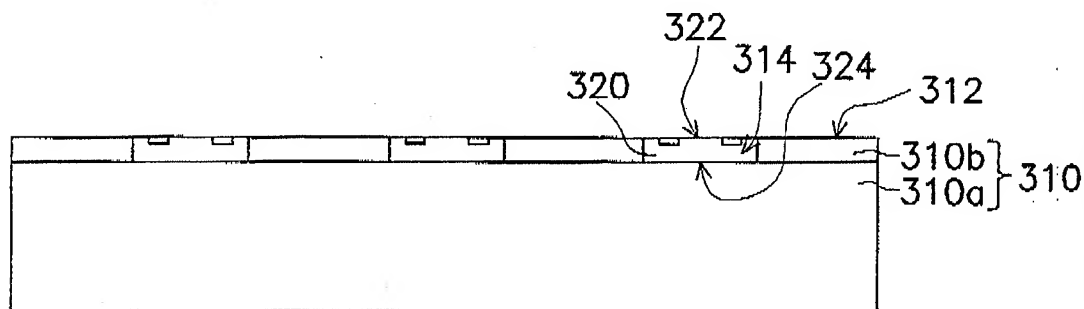


FIG. 3C

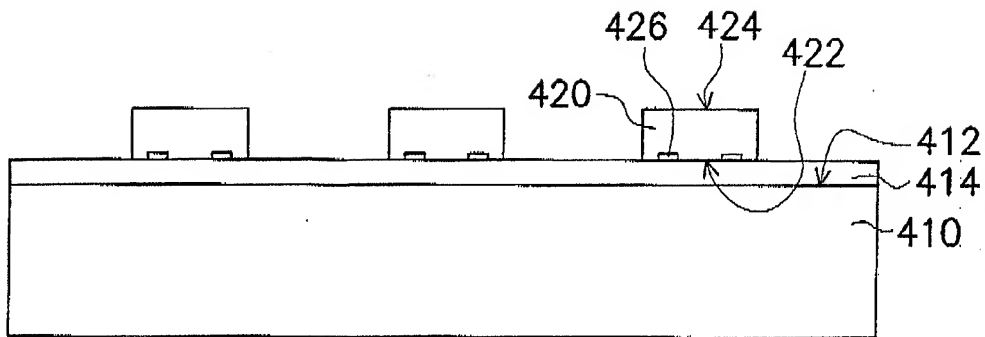


FIG. 4A

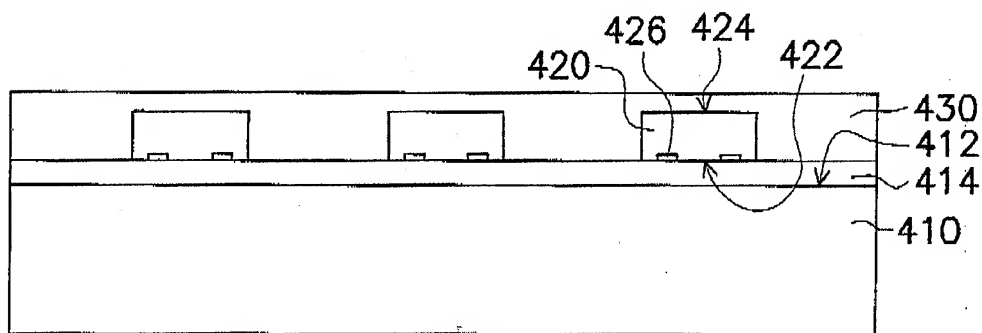


FIG. 4B

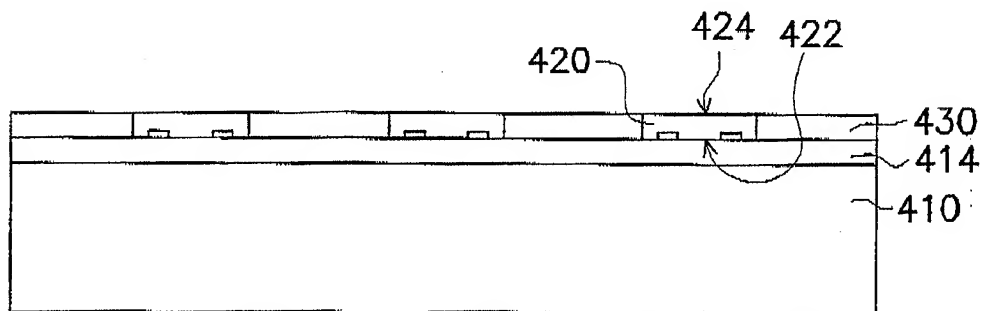


FIG. 4C

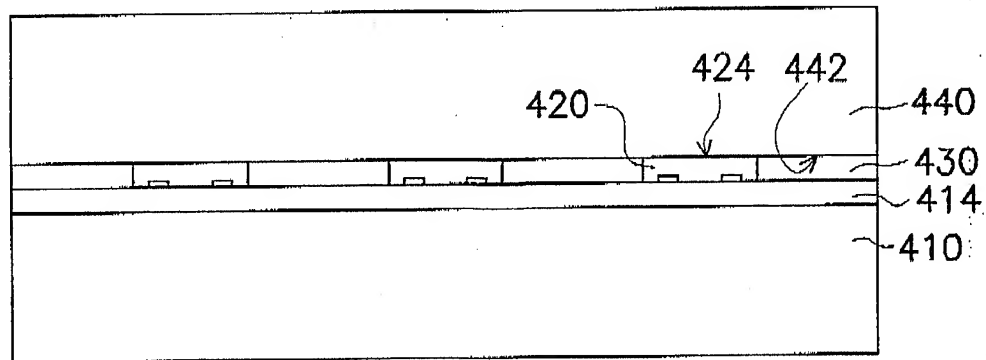


FIG. 4D

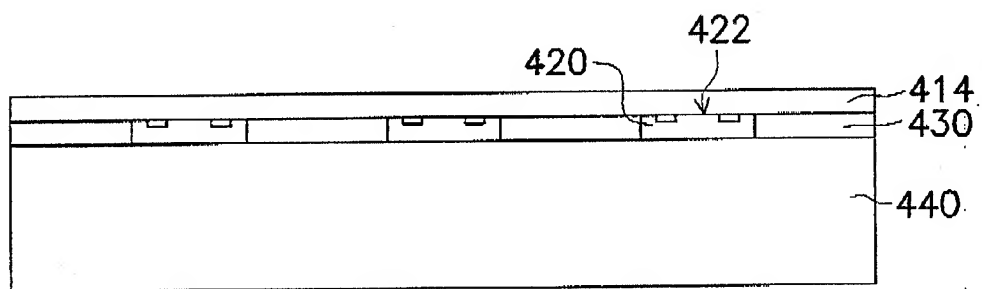


FIG. 4E

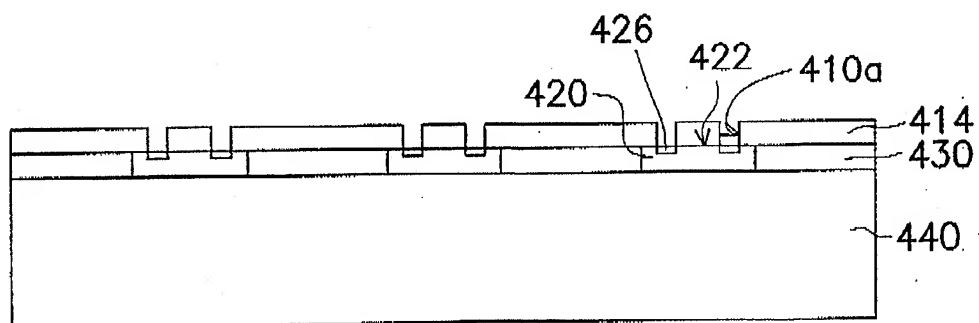


FIG. 4F

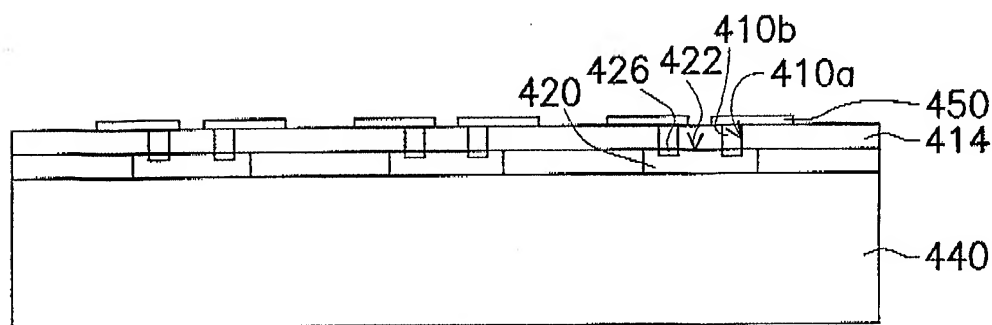


FIG. 4G

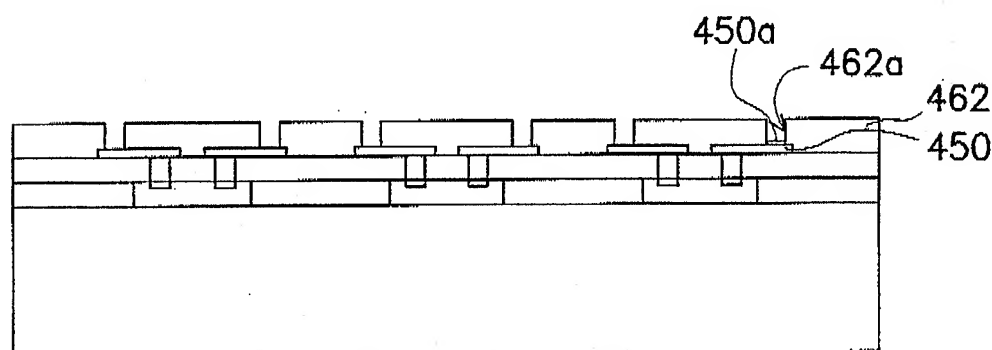


FIG. 4H

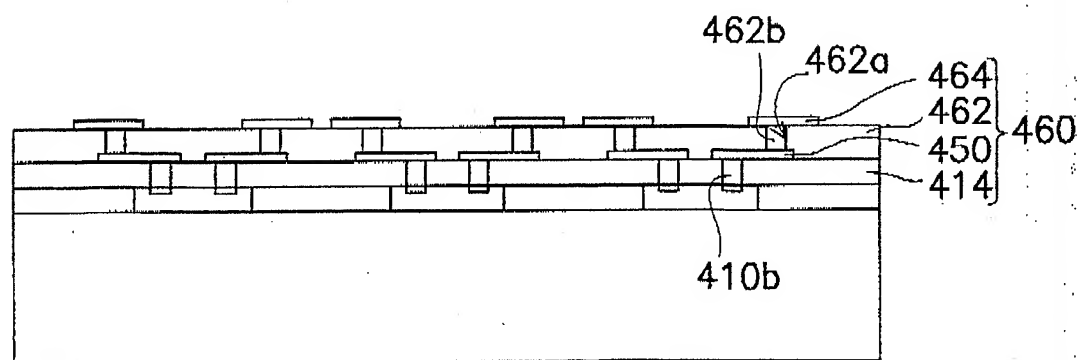


FIG. 4I



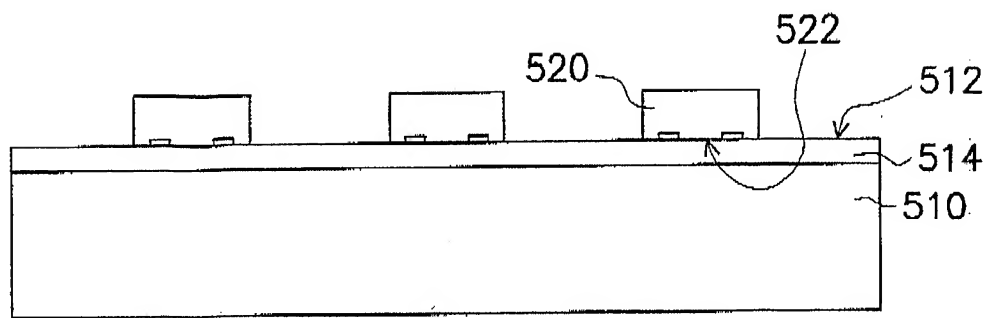


FIG. 5A

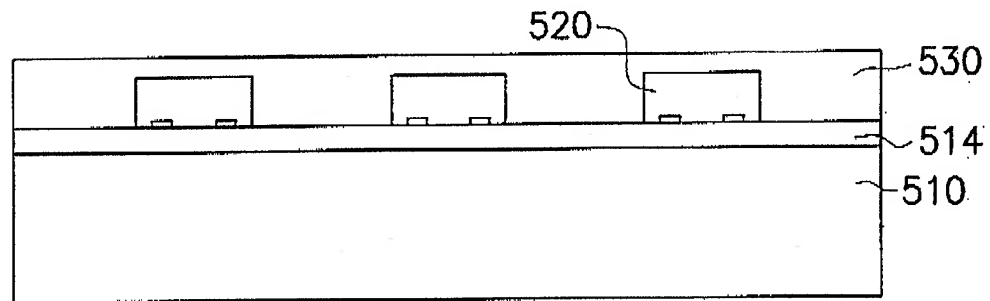


FIG. 5B

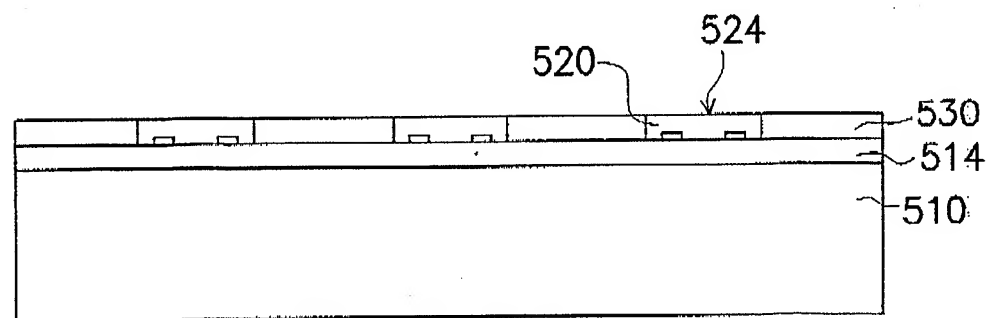


FIG. 5C

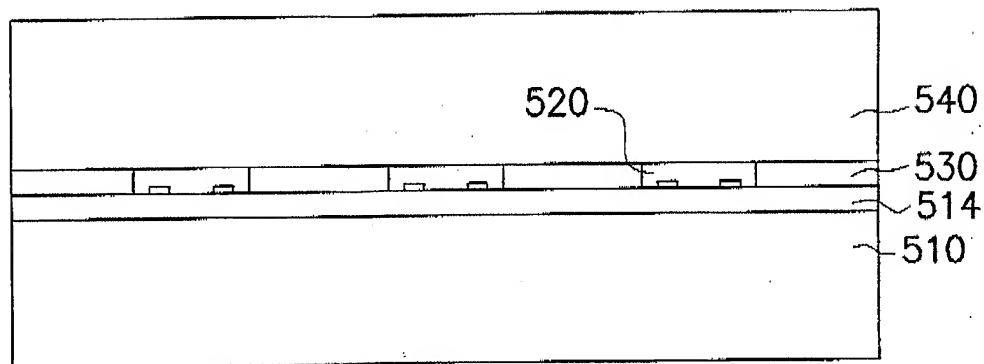


FIG. 5D

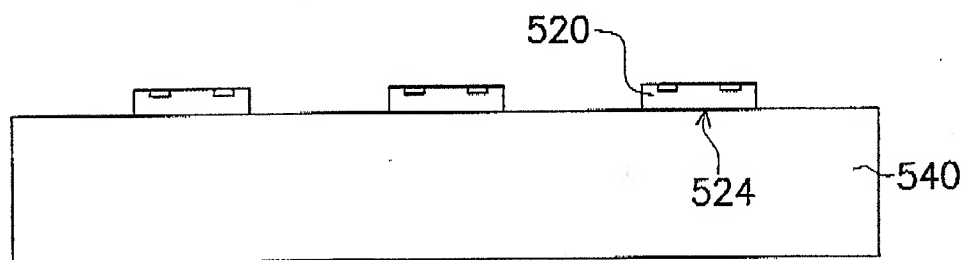


FIG. 5E

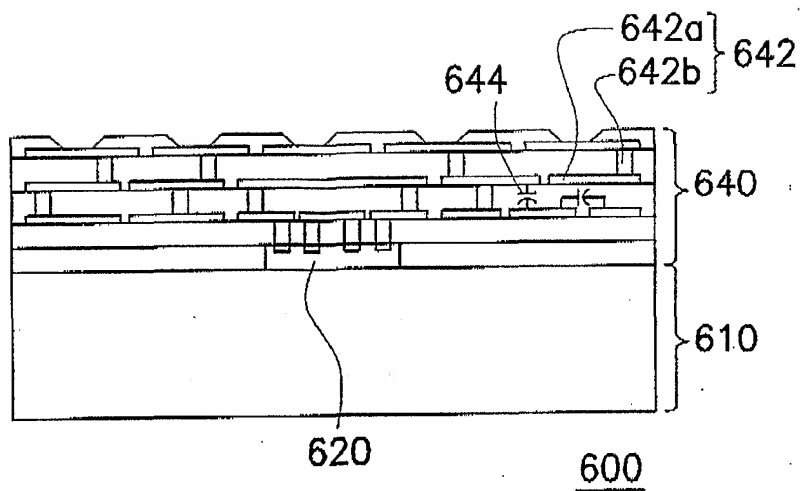


FIG. 6

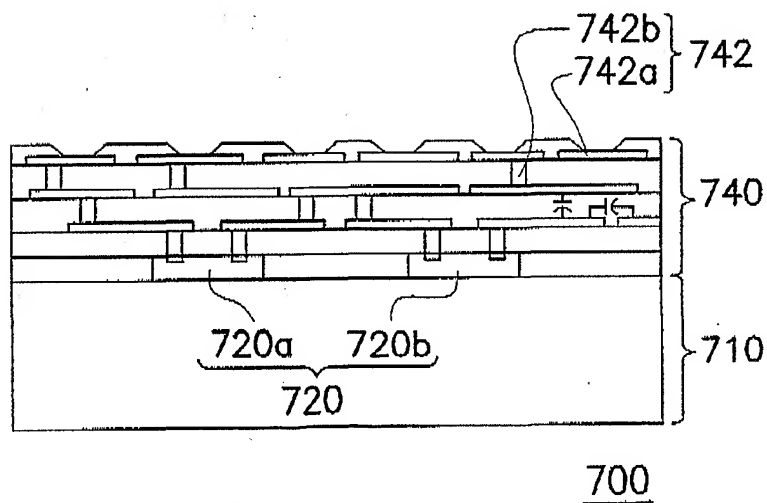


FIG. 7

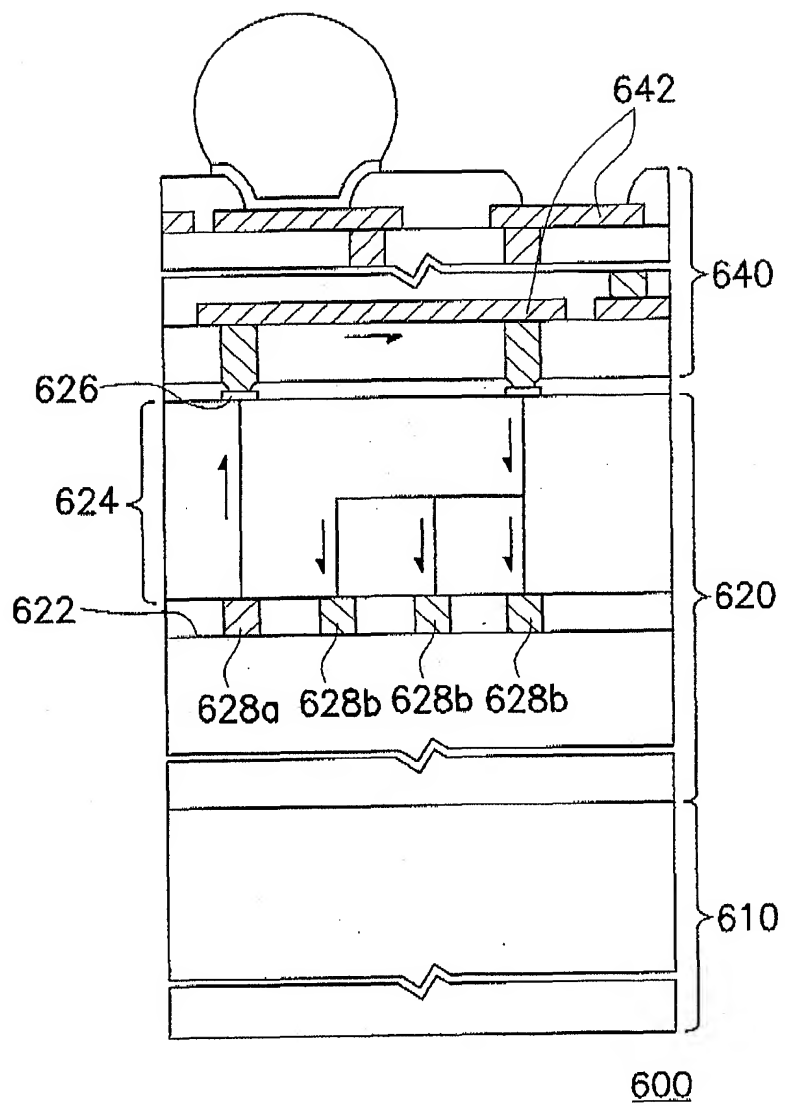


FIG. 8

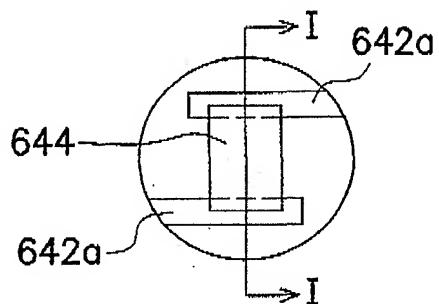


FIG. 9A

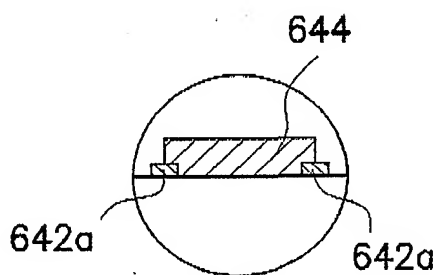


FIG. 9B

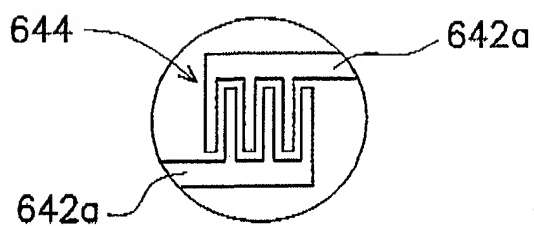


FIG. 10A

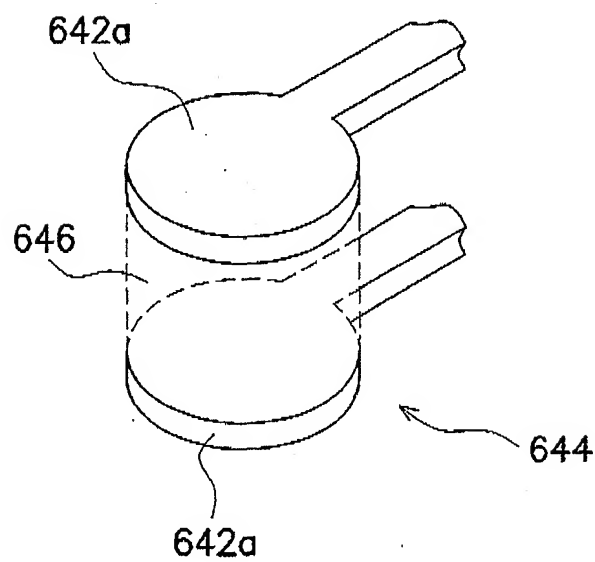


FIG. 10B

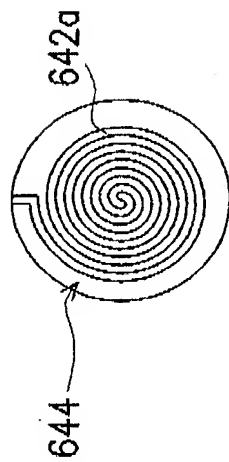


FIG. 11A

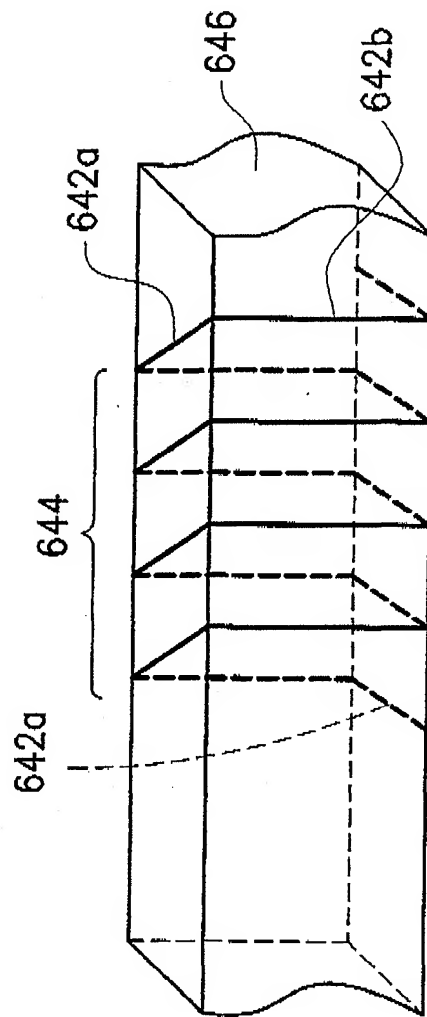


FIG. 11B

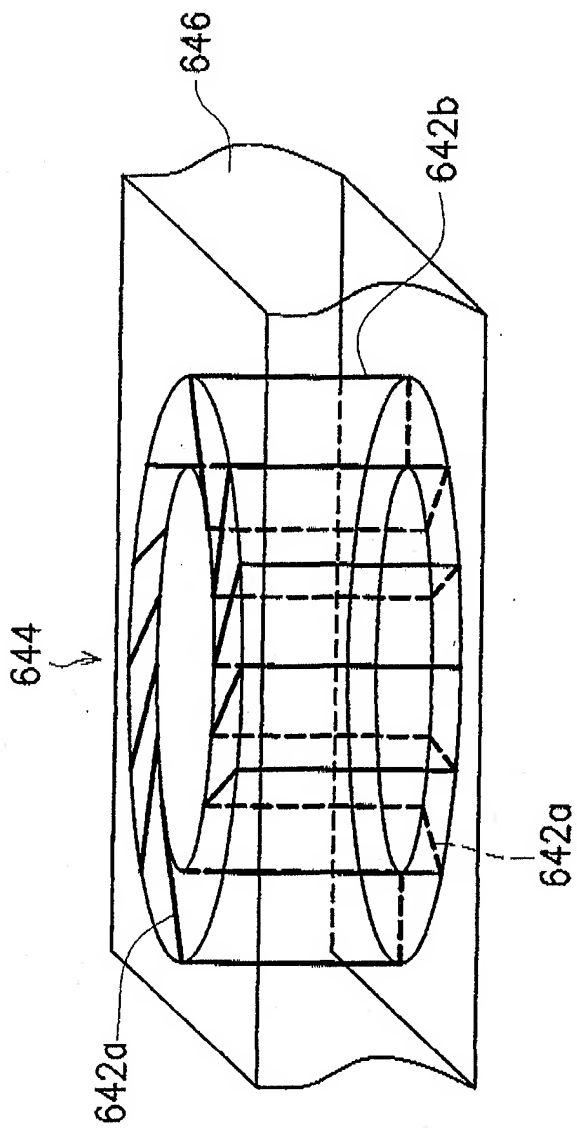


FIG. 11C